

IN THE SPECIFICATION

On page 3, line 20, please delete "side elevation" and insert --partial cross-sectional--.

On page 3, line 21, please delete "side elevation" and insert --partial cross-sectional--.

On page 3, line 23, please delete "side elevation" and insert --cross-sectional--.

On page 3, line 24, please delete "side elevation" and insert --cross-sectional--.

On page 3, line 25, please delete "side elevation" and insert --partial cross-sectional--.

On page 8, line 5, please delete "416" and insert --417--.

On page 8, line 18, please delete "412" and insert --414--.

IN THE CLAIMS

Please amend claims 1, 9, 11, 12, 18, 20, 21 and 22, as follows:

*Sub B* *A1*

1. (Amended) A solderless mounting socket, comprising:  
a socket body having a first side and a second, opposite side, the body having a plurality  
of vias extending therethrough;  
a plurality of solderless conductive terminals within the vias, wherein the terminals  
comprise:  
an elastically deformable member.

*Sub B3* *A2*

9. (Amended) A method of mounting a socket to a board, the socket having a plurality of  
solderless compressible contact terminals, comprising:  
applying an adhesive layer to a board side of the socket;  
leveling the adhesive layer to make the adhesive layer substantially coplanar with the  
solderless compressible contact terminals of the socket; and  
adhering the socket to the board compressing the plurality of solderless compressible  
contact terminals against complementary electrical contacts on the board.

*Sub P4*

11. (Amended) A method of mounting a package to a board using a socket having solderless compressible contact terminals, the method comprising:  
applying a first adhesive layer to a first, package side of the socket;  
leveling the first adhesive layer to make the adhesive layer substantially coplanar with the solderless compressible contact terminals;  
adhering the package to the first adhesive layer;  
applying a second adhesive layer to a second, board side of the socket;  
leveling the second adhesive layer to make the second adhesive layer substantially coplanar with the solderless compressible contact terminals; and  
adhering the board to the second adhesive layer compressing the solderless compressible contact terminals against complementary electrical contacts on the board.

*A3*

12. (Amended) A solderless circuit interconnect, comprising:  
a circuit board carrier having a plurality of through holes formed therein; and  
a plurality of solderless conductive terminals with lands at each end, each terminal in one of the through holes, wherein each conductive terminal comprises an elastically deformable member.

*Sub Q4*

18. (Amended) A circuit package, comprising:  
a substrate having a plurality of solderless conductive terminals therethrough;  
a first adhesive layer affixed to a first side of the substrate; and  
a package affixed to the first adhesive layer.

*Sub P1*

20. (Amended) An integrated circuit, comprising:  
a substrate having a plurality of vias therein; and  
a plurality of elastically deformable solderless terminals, each terminal positioned in a via.

*A5*

21. (Amended) A circuit assembly, comprising:  
a substrate having a built-in socket, the socket having a plurality of vias therein;